

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT(S) : Eliashevich et al.

FOR : OPTIMIZED CONTACT DESIGN FOR  
THERMOSONIC BONDING OF FLIP-  
CHIP DEVICES

SERIAL NO. : 10/588,473

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EXAMINER : Jose R. Diaz

ART UNIT : 2815

CONFIRMATION NO. : 6709

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Kindly enter the "Fee Address" for the above-identified application, as follows:

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Respectfully submitted,  
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Date: <i>Jan. 6, 2010</i>	<i>Mary Ann Temesvari</i> Name: Mary Ann Temesvari